

BTECH
(SEM-VII) THEORY EXAMINATION 2022-23
MICRO & SMART SYSTEMS

Time: 3Hours

Total Marks:100

Note:1. Attempt all Sections. If require any missing data; then choose suitably.

2. Any special paper specific instruction.

SECTION A

1. Attempt *all* questions in brief.

$$2 \times 10 = 20$$

- (a) What is the difference between Micro systems versus MEMS?
- (b) What do you mean by smart systems?
- (c) Give the applications of smart materials and Microsystems.
- (d) Which transducer is known as 'self-generating transducer'?
- (e) Explain micromachining process.
- (f) What is dynamic range?
- (g) Write the applications of piezo-resistive pressure sensor?
- (h) What is the use of Hall Effect sensors?
- (i) What is the difference between tactile and non-tactile sensor?
- (j) Define intelligent sensor.

SECTION B

2. Attempt any *three* of the following:

10x3=30

- Explain in detail Silicon capacitive accelerometer.
- What are the goals and applications of integrated Microsystem?
- What are smart-material systems? Evolution of smart materials, structures and systems.
- Explain Micro machined transducers. Evolution of micro-manufacturing. Applications areas.
- Describe and salient features of sensors, actuators, and systems.

SECTIONC

3. Attempt any *one* part of the following:

10x1=10

- Describe piezoelectric inkjet print head and their characteristics.
- Discuss in detail about piezo-resistive pressure sensor.

4. Attempt any *one* part of the following:

10x1=10

- Write a short note on advanced processes for micro fabrication.
- Explain the emerging trends in Silicon wafer processing.

5. Attempt any *one* part of the following:

10x1=10

- Describe Poisson effect and the anticlastic curvature of beams.
- Explain modeling of coupled electromechanical systems.

6. Attempt any *one* part of the following:

10x1=10

- What is residual stress and stress gradients? Give difference between them.
- Explain integration of Microsystems and microelectronics.

7. Attempt any *one* part of the following:

10x1=10

- Explain in brief microsystems packaging.
- Describe mechanical domain, electrostatic domain, and magnetic domain.